





# JN Semiconductor®

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August 2014

## FQP15P12 / FQPF15P12 P-Channel QFET® MOSFET

-120 V, -15 A, 0.2  $\Omega$ 

## **Description**

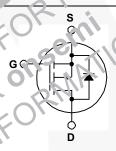
This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor<sup>®</sup>'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

### **Features**

- -15 A, -120 V,  $R_{DS(on)} = 0.2 \Omega$  (Max.) @ V 10 V,  $I_D = -7.5$  A
- · Low Gate Charge (Typ. 29 nC)
- Low Crss (Typ. 110 pF)
- 100% Avalanche Tested
- 175°C Maximum Junc. Te. eratur Rating







## Absolute Max num Ra. 3

: 25°C unless other vise noted

Symbol	Parameter		FQP15P12	FQPF15P12	Unit
V <sub>DSS</sub>	Droi Sou Jitage		-120		V
I <sub>D</sub>	rain rrent Continuous (T <sub>C</sub> = 2.5°C	()	-15	-15 *	Α
	- Continuous (T <sub>C</sub> = 100	C)	-10.6	-10.6 *	Α
I <sub>DM</sub>	Drain Current - Priisec	(Note 1)	-60	-60 *	Α
V <sub>GS</sub>	Gate-Source Volta 0:		± 30		V
	Single Pulsed Avalancha Energy	(Note 2)	1157		mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	-15		Α
F,R	Repetitive Avalanche Energy	(Note 1)	10		mJ
tb/vt	Peak Diode Recovery dv/dt	(Note 3)	-5.0		V/ns
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C)		100	41	W
	- Derate above 25°C		0.67	0.27	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +175		°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300		°C

<sup>\*</sup> Drain current limited by maximum junction temperature.

### **Thermal Characteristics**

Symbol	Parameter	FQP15P12	FQPF15P12	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.5	3.66	°C/W
$R_{\theta JS}$	Thermal Resistance, Case-to-Sink Typ.	40		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	-120			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, Referenced to 25°C		-0.13		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -120 V, V <sub>GS</sub> = 0 V			-1	μΑ
		V <sub>DS</sub> = -96 V, T <sub>C</sub> = 150°C			-10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V			-100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
On Cha	aracteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$			<u>-4,r</u>	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -7.5 A		0.17	0.2	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = -40 V, I <sub>D</sub> = -7.5 A	<b>—</b>	J.5	7.7/	S
<b>Dynam</b> C <sub>iss</sub>	ic Characteristics Input Capacitance	V <sub>DS</sub> = 2t V <sub>G</sub> = 0.		850	1100	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 20$ $V_{G} = 0$		310		r.F
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 5 WHZ		G13	140	ρF
	ing Characteristics	OF	O	13.1	7	
t <sub>d(on)</sub>	Turn-On Delay Time			15	40	ns
t <sub>r</sub>	Turn-On Rise Time	$_{0} = -60 \text{ V} \cdot 1_{0} = -15 \text{ A}$		100	210	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$R_G = 25 \Omega$		80	170	ns
t <sub>f</sub>	Turn-Off F , mule	(Note 4)		80	170	ns
Q <sub>g</sub>	Total Gat Charge	V <sub>DS</sub> = -9° V; i <sub>D</sub> = -15 A		29	38	nC
Q <sub>gs</sub>	alc Soul Char	V <sub>GS</sub> = -10 V		5.1		nC
Q <sub>gd</sub>	n Charge	(Note 4)		15		nC
			Į.			
ь. in-	nuice Diode Characteristics at	nd Maximum Ratings				
Is	naximum Continuous Litair -Source Dinde Forward Current				-15	Α
I <sub>SM</sub>	Maximum Pulseri Drain-Source Diode Forward Current				-60	Α
SD \	Lirain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -15 A			-4.0	V
t <sub>rr</sub>	Reverse Recovery Tinus	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -15 A,		126		ns

- **Notes:**1. Repetitive rating : pulse \*\*\*\omega\_{\text{times}}\$ limited by maximum junction temperature. 2. L = 6.0mH, I<sub>AS</sub> = -15A, V<sub>LD</sub> = -50V, R<sub>G</sub> = 25 \Omega\_{\text{s}}\$ starting T<sub>J</sub> = 25°C. 3. I<sub>SD</sub> \le -15A, di/dt \le 300A/\text{µs}, V<sub>DD</sub> \le BV<sub>DSS</sub>, starting T<sub>J</sub> = 25°C. 4. Essentially independent of operating temperature.

## **Typical Characteristics**

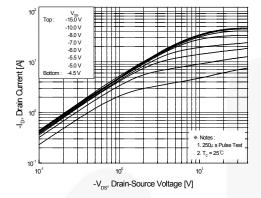
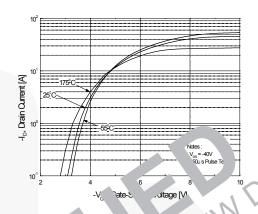


Figure 1. On-Region Characteristics



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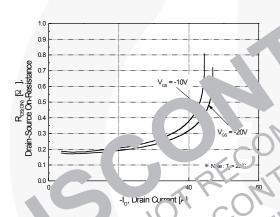


Fig. . . 3. On-Resistance Variation vo Drain Current and Gate Voltage

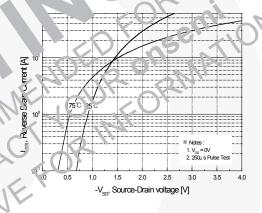


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

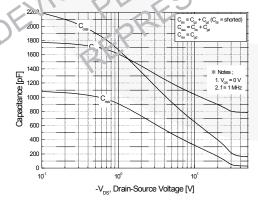


Figure 5. Capacitance Characteristics

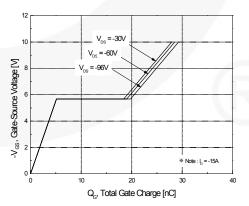


Figure 6. Gate Charge Characteristics

## Typical Characteristics (Continued)

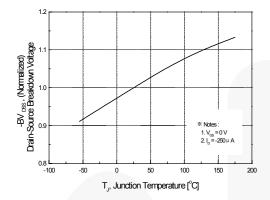
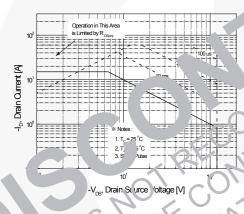


Figure 7. Breakdown Voltage Variation vs Temperature

qui . On-i sistance Valiation



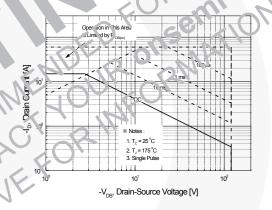


Fig. re 9-1. Maximum Safe Operating Area for FQP15512

Figure 9-2. Maximum Safe Operating Area for FQPF15P12

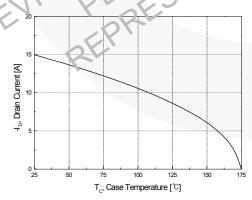


Figure 10. Maximum Drain Current vs Case Temperature

## Typical Characteristics (Continued)

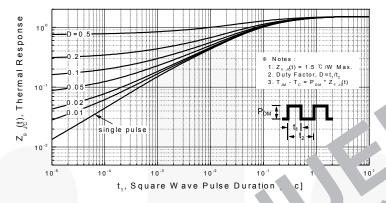


Figure 11-1. Transient Thermal Response Cove to 15P12

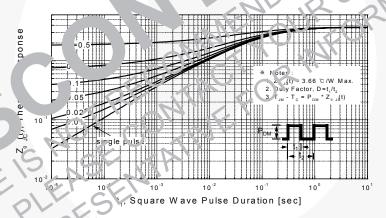


Figure 11-2. Transient Thermal Response Curve for FQPF15P12

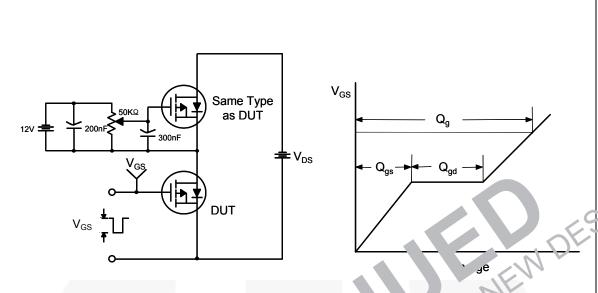


Figure 12. Gate Charge Test Cocuit & Vav.



Figure 13. Resistive Switching Test Circuit & Waveforms

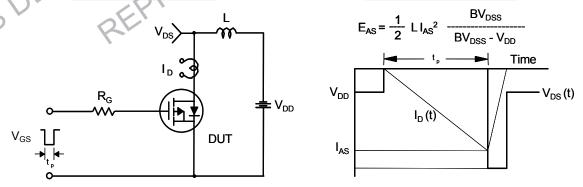
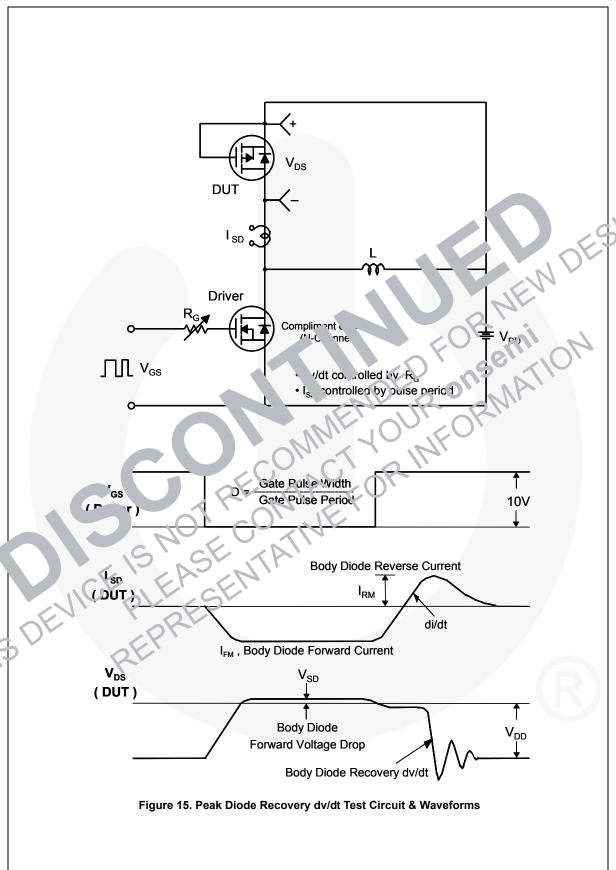
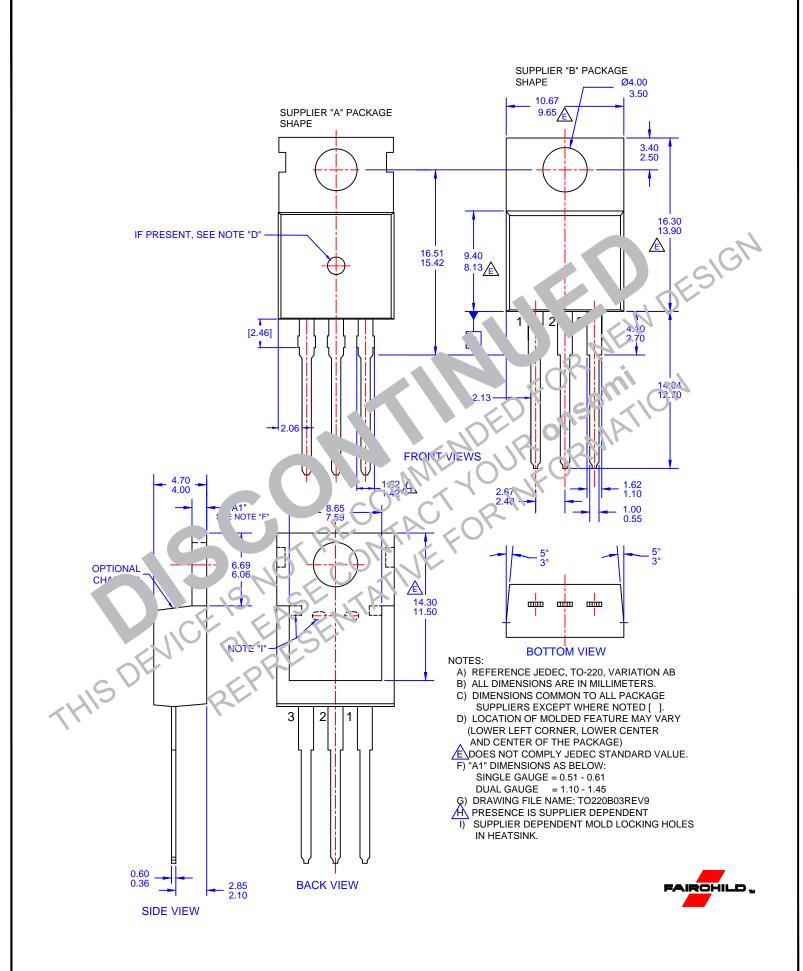
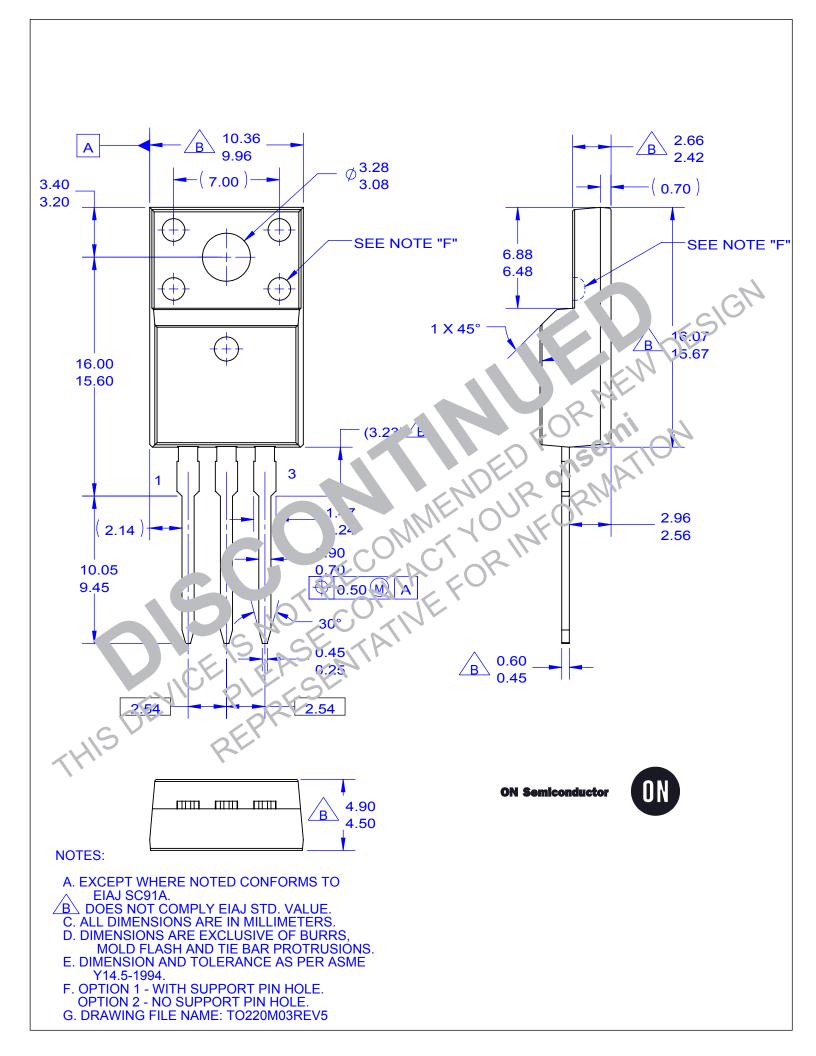


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms









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